

Listing of Claims:

1. (Currently Amended) A wafer-interposer assembly comprising:

a semiconductor wafer including a plurality of semiconductor die, each semiconductor die having a plurality of first electrical contact pads;

an interposer non-temporarily electrically and mechanically connected to the semiconductor wafer, the interposer including a plurality of second electrical contact pads respectively connected to at least some of the first electrical contact pads via conductive attachment elements such that the interposer and the semiconductor wafer are operable to be singulated into a plurality of chip assemblies; and

a communication interface integrally associated with the interposer and electrically connected to at least some of the second electrical contact pads.

2. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises an integral edge connector with pins.

3. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises an integral bayonet connector with pins.

4. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises a connector added to the wafer-interposer assembly.

5. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises soldered connections.

6. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises a ribbon connector.

7. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises an RF connector.

8. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises an optical connector.

9. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises a transmit/receive antenna.

10. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface further comprises a quick release device.

11. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface is operably coupled to a testing apparatus that tests at least some of the semiconductor die prior to the singulation of the interposer and the semiconductor wafer.

12. (Original) The wafer-interposer assembly as recited in claim 1 wherein the communication interface is operably coupled to a testing apparatus that burn-in tests at least some of the semiconductor die prior to the singulation of the interposer and the semiconductor wafer.

Please cancel claims 13-25.

26. (New) A wafer-interposer assembly comprising:

a semiconductor wafer including a plurality of semiconductor die having a pattern of first electrical contact pads disposed thereon;

an interposer connected to the semiconductor wafer, the interposer having a first surface with a pattern of second electrical contact pads disposed thereon, at least some of which correspond to and are non-temporarily electrically and mechanically connected to at least some of the first electrical contact pads via conductive attachment elements, the interposer also having a second surface having a pattern of third electrical contact pads that are electrically connected to at least some of the second electrical contact pads, such that the interposer and the semiconductor wafer are operable to be singulated into a plurality of chip assemblies, each including a semiconductor die and a portion of the interposer that remain connected to one another; and

a communication interface integrally associated with the interposer and electrically connected to at least some of the second electrical contact pads.

27. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface further comprises an integral edge connector with pins.

28. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface further comprises an integral bayonet connector with pins.

29. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface further comprises a connector added to the wafer-interposer assembly.

30. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface further comprises soldered connections.

31. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface further comprises a ribbon connector.

32. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface further comprises an RF connector.

33. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface further comprises an optical connector.

34. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface further comprises a transmit/receive antenna.

35. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface further comprises a quick release device.

36. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface is operably coupled to a testing apparatus that tests at least some of the semiconductor die prior to the singulation of the interposer and the semiconductor wafer.

37. (New) The wafer-interposer assembly as recited in claim 26 wherein the communication interface is operably coupled to a testing apparatus that burn-in tests at least some of the semiconductor die prior to the singulation of the interposer and the semiconductor wafer.